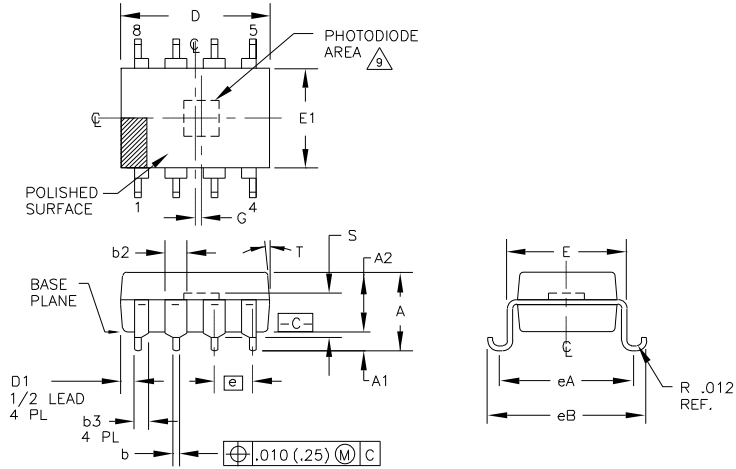


Package Number 006-6 - Transparent J-Formed 8-Lead Surface-Mount DIP



DIM	INCHES		MILLIMETERS		N	E	DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.		
A	--	.255	--	6.48			N	.100	.120	2.54	3.05		
A1	.040	.060	1.02	1.52			S	5.5*	8.5*	5.5*	8.5*		
A2	.120	.135	3.05	3.43									
b	.014	.022	0.36	0.56									
b2	.040	.050	1.02	1.27	5								
b3	.030	.045	0.76	1.14	5								
D	.360	.390	9.14	9.91	3								
D1	.005	--	0.13	--	3								
E	.300	.325	7.62	8.26									
E1	.238	.275	6.05	6.99	3								
e	.100	BASIC	2.54	BASIC									
eA	.350	.370	8.89	9.40									
eB	--	.415	--	10.54									
G	.011	.021	0.28	0.53									

NOTES:

1. ALL DIMENSIONS ARE IN INCHES.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
3. D, D1, AND E1 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
4. N IS THE MAXIMUM OF TERMINAL POSITIONS.
5. b2 AND b3 MAXIMUM DIMENSIONS DO NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).
6. DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 (0.13mm) MINIMUM.

7. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

8. FOR AUTOMATIC INSERTION, ANY RAISED IRREGULARITY ON THE TOP SURFACE (STEP, MESA, ETC.) SHALL BE SYMMETRICAL ABOUT THE LATERAL AND LONGITUDINAL PACKAGE CENTERLINES.

9. CENTER OF PHOTODIODE MUST BE WITHIN .010 (0.25mm) OF CENTER OF PHOTODIODE AREA.

PACKAGE NUMBER: ZZ006-6    REV.: B  
JEDEC NUMBER: NONE



PACKAGE DRAWING

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